

# **TOSHIBA CMOS Integrated Circuits Silicon Monolithic**

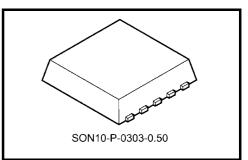
# TCA62723FMG

# **Three-Channel Constant-Current LED Driver**

The TCA62723FMG is an optimal constant-current LED driver for RGB pixel LEDs.

Moreover, it is not necessary to connect external resistance to an output in almost all cases.

The forward current of the LED is set up using the external resistor.



Weight: 0.018 g (typ.)

## Features

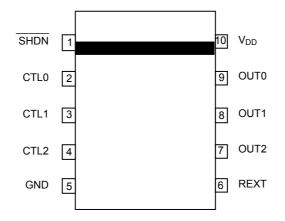
- Power supply voltage range
- Constant current range
- Low consumption current
  - Supply current at operation (lout = 20 mA/DC) Supply current at standby
  - For anode common LED
- Package

- : VIN = 2.7 to 5.5 V
- : 5 to 150 mA
- : 700 µA(MAX)
- : 1 μA(MAX)
- : SON10-P-0303-0.50 height : 0.8 mm(Typ.)

# Pin Layout (Top view)

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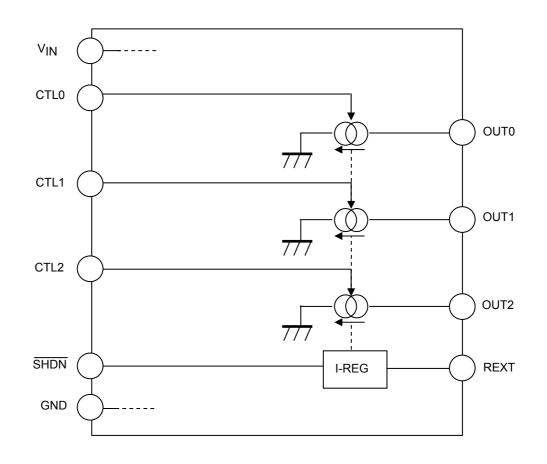
TENTATIVE



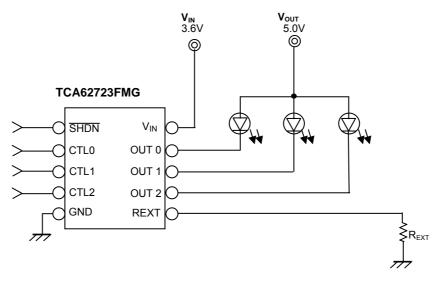
#### **Terminal Description**

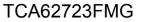
Pin No.	Pin Name	Function				
1	SHDN	Input pin for IC ON/OFF control. When the data is "H", the IC operates; When the data is "L", power-saving mode applies.				
2	CTL0	Input pin for OUT0 ON/OFF control. When the data is "H, OUT0 is turned on; When the data is "L", OUT0 is turned off.				
3	CTL1	Input pin for OUT1 ON/OFF control. When the data is "H, OUT1 is turned on; When the data is "L", OUT1 is turned off.				
4	CTL2	Input pin for OUT3 ON/OFF control. When the data is "H, OUT3 is turned on; When the data is "L", OUT3 is turned off.				
5	GND	GND terminal				
6	REXT	This is an output current setting resistor connect terminal. The output current does not flow when this terminal is opened. Excessive output current will destroy the IC if this terminal is connected to GND.				
7	OUT2					
8	OUT1	Output terminal				
9	OUT0					
10	V <sub>IN</sub>	2.7 V to 5.5 V supply voltage terminal				

TOSHIBA TENTATIVE Block Diagram



# **Application Circuit Example**

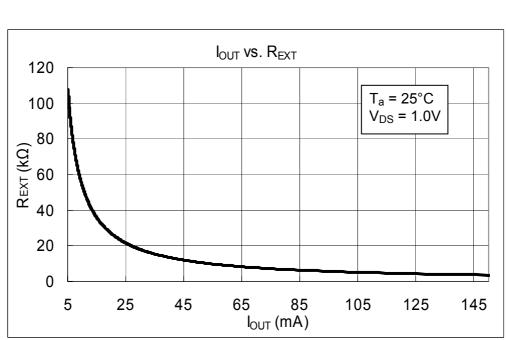




#### Method of setting IOUT

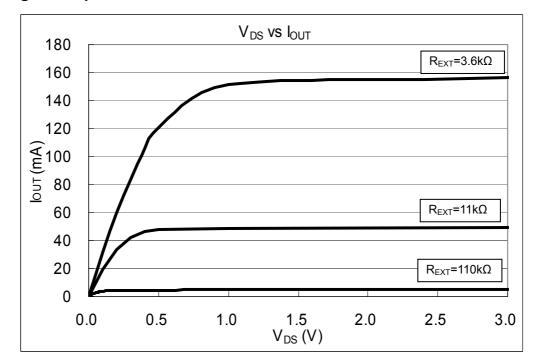
TOSHIBA

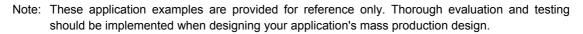
The current of the terminal OUT0 to 2 is set by resistance connected with the terminal REXT.  $I_{\text{OUT}}$  can be set according to the next expression.



$$I_{OUT}$$
 (mA) =  $\frac{1.17 (V)}{R_{EXT} (k\Omega)} \times 460$ 

**Output Voltage – Output Current** 





# **TOSHIBA**

#### TENTATIVE Current Dimming Control

#### 1) Input analog voltage to REXT terminal

1. Precondition

Please set the range of the analog voltage input by 0 to 1.17V.

2. The maximum current is defined as  $\alpha mA$ . (V<sub>ADJ</sub>=0V)

$$\alpha = 1.17 \times \frac{R_1 + R_{EXT}}{R_1 \times R_{EXT}} \times 460$$

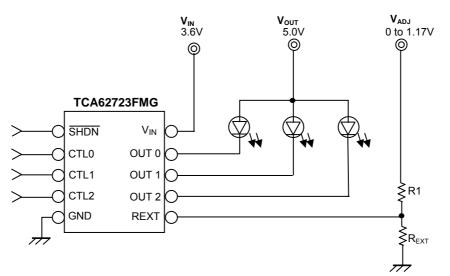
3. A minimum current is defined as  $\beta$ mA. (V<sub>ADJ</sub>=1.1V)

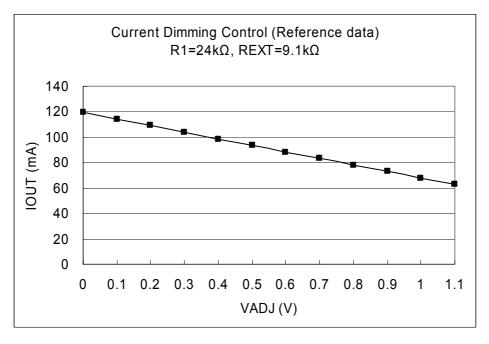
$$\beta = 1.17 \times \frac{1}{R_{EXT}} \times 460$$

4.  $I_{\mbox{\scriptsize OUT}}$  can be set according to the next expression.

$$I_{OUT} = V_{ADJ} \times \frac{\beta - \alpha}{1.17} + \alpha$$

(Example) Current Dimming from I<sub>OUT</sub>=120mA to 60mA (Reference data)



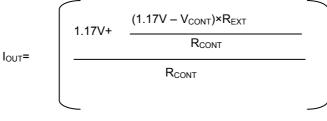


Note: These application examples are provided for reference only. Thorough evaluation and testing should be implemented when designing your application's mass production design.

#### **TENTATIVE** 2) Input PWM signal to REXT terminal

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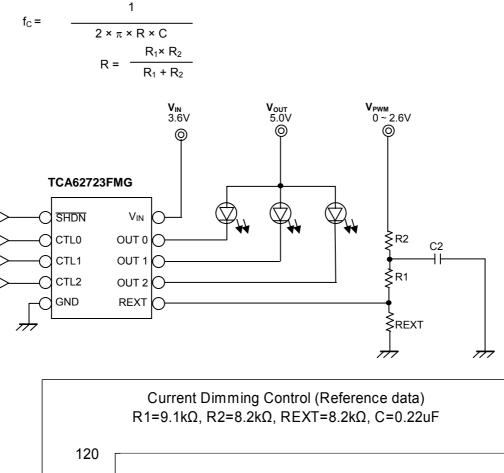
 $I_{OUT}$  can be set according to the next expression.

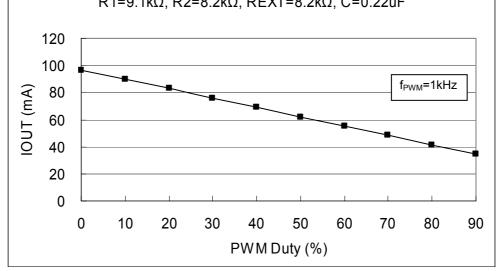


V<sub>CONT</sub>=D×V<sub>PWM</sub> D: PWM Duty (%)

R<sub>CONT</sub>=R<sub>1</sub>+R<sub>2</sub>

Please define the cutoff frequency to the next expression. ( $f_C \le f_{PWM}$ )





Note: These application examples are provided for reference only. Thorough evaluation and testing should be implemented when designing your application's mass production design.

## TOSHIBA TENTATIVE

#### Maximum Ratings ( $T_a = 25^{\circ}C$ )

Characteristic	Symbol	Ratings	Unit
Supply voltage	V <sub>IN</sub>	-0.3 ~ +6.0	V
Output voltage	V <sub>OUT</sub>	-0.3 ~ +6.0	V
Input voltage	V <sub>IN</sub>	−0.3 ~ V <sub>IN</sub> +0.3 *Note1	mA
Devendingingtion	Б	0.36 (free air)	
Power dissipation	PD	0.79 (on PCB) *Note2	W
	_	340 (free air)	
Thermal resistance	R <sub>th (j-a)</sub>	158 (on PCB)	°C/W
Operating temperature	emperature $T_{opr}$ $-40 \sim +85$		°C
Storage temperature	T <sub>stg</sub>	-55 ~ +150	°C
Maximum junction temperature	Tj	150	°C

Note1 : However, do not exceed 6V.

Note: Subtract 3.8 mW / degree from the maximum rating value about a degree if the operation temperature exceeds 25°C when the device is mounted on a PCB.

#### **Recommended Operating Condition**

Characteristic	Symbol	Condition	Min	Тур.	Мах	Unit
Supply voltage	V <sub>DD</sub>	-	2.7	3.6	5.5	V
Constant current output	I <sub>OUT</sub>	OUT0 to OUT2	5	-	150	mA/ch
R <sub>EXT</sub>	R <sub>EXT</sub>	-	3.6	-	110	kΩ
CTL terminal minimum pulse width	t <sub>CTL</sub>	R <sub>EXT</sub> =11kΩ	25	-	-	mA

#### Electrical Characteristics (unless otherwise specified, $V_{IN} = 3.6 V$ , $T_a = 25^{\circ}C$ )

Characteristic		Symbol	Condition	Min	Тур	Мах	Unit
Supply voltage		V <sub>IN</sub>	-	2.7	3.6	5.5	V
Supply current (IC operation)		I <sub>IN</sub> (On)	R <sub>EXT</sub> = 27.6kΩ	-	-	700	μA
Supply current (IC standby)		I <sub>IN</sub> (Off)	SHDN = L	-	-	1.0	μA
Input voltage	High level	V <sub>IH</sub>	CTL0,CTL1,CTL2,SHDN	$0.7 V_{\text{IN}}$	-	V <sub>IN</sub> +0.15V	v
	Low level	VIL	CTL0,CTL1,CTL2,SHDN	-0.15	-	0.3V <sub>IN</sub>	
Input current		I <sub>IH</sub>	CTL0,CTL1,CTL2,SHDN	-1.0	-	1.0	μA
		IIL	CTL0,CTL1,CTL2,SHDN	-1.0	-	1.0	
Gain		GAIN	$I_{OUT}/I_{REXT}$ , $R_{EXT}$ = 11 k $\Omega$	380	460	560	A/A
REXT terminal voltage		V <sub>REXT</sub>	$V_{IN}$ =3.6 V, $R_{EXT}$ = 11 k $\Omega$	1.1	1.17	1.24	V
Output leakage current		l <sub>oz</sub>	$\overline{\text{SHDN}}$ = "L", $V_{\text{OUT}}$ = 5.5 V	-	-	0.1	μΑ
Constant current accuracy between bits		dl <sub>out</sub>	V <sub>IN</sub> = 3.6 V, R <sub>EXT</sub> = 11 kΩ	-	±1	±7.5	%
Time from SHDN release to start of operation		t <sub>RE</sub>	-	-	2	5	ms

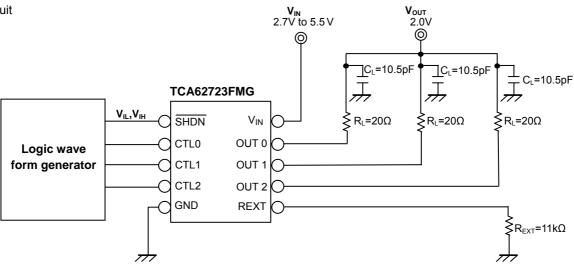
#### TOSHIBA TENTATIVE

#### Switching characteristic (unless otherwise specified, $V_{IN} = 3.6 V$ , $T_a = 25^{\circ}C$ )

Characteristic	Symbol	Condition	Min	Тур	MAX	Unit
Description to be	tpLH	R <sub>EXT</sub> = 11kΩ	-	50	-	ns
Propagation delay	tpHL	R <sub>EXT</sub> = 11kΩ	-	1	-	μs
Rise time	tR	R <sub>EXT</sub> = 11kΩ	-	50	-	ns
Fall time	tF	R <sub>EXT</sub> = 11kΩ	-	500	-	ns

Note:  $T_a = 25^{\circ}C$ ,  $V_{DD} = V_{IH} = 2.7V$  or 5.5V,  $V_{OUT}=2.0V$ ,  $V_{IL} = 0V$ ,  $R_L = 20\Omega$ ,  $C_L = 10.5pF$ 

Test Circuit



## TCA62723FMG

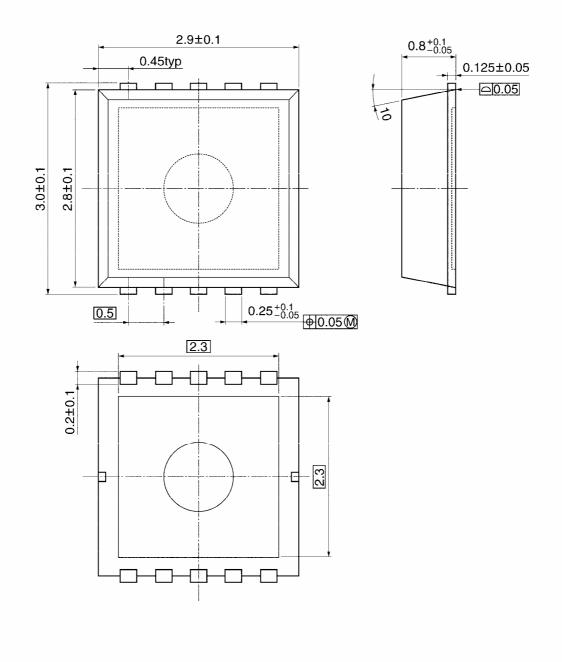
# Package Dimensions

TOSHIBA

TENTATIVE

SON10-P-0303-0.50

Unit: mm



Weight: 0.016 g (typ.)

## TCA62723FMG

# Notes on Contents

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#### **Block Diagrams**

Some functional blocks, circuits, or constants may be omitted or simplified in the block diagram for explanatory purposes.

#### **Maximum Ratings**

The absolute maximum ratings of a semiconductor device are a set of specified parameter values that must not be exceeded during operation, even for an instant.

If any of these ratings are exceeded during operation, the electrical characteristics of the device may be irreparably altered and the reliability and lifetime of the device can no longer be guaranteed.

Moreover, any exceeding of the ratings during operation may cause breakdown, damage and/or degradation in other equipment. Applications using the device should be designed so that no maximum rating will ever be exceeded under any operating conditions.

Before using, creating and/or producing designs, refer to and comply with the precautions and conditions set forth in this document.

#### **Application Examples**

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#### Handling of the IC

- Ensure that the product is installed correctly to prevent breakdown, damage and/or degradation in the product or equipment.
- Short circuiting between output and line to ground faults may result in damage to the IC. Please exercise precaution in designing the output line, power line and GND line so as to prevent such damage.
- Be careful to insert the IC correctly. Inserting the IC the wrong way (e.g., wrong direction) may result in damage to the IC.
- Please exercise precaution in handling external components as shorting and opening such components may cause an overcurrent, which in turn may result in power overcurrent and/or in damage to the IC.

About solderability, following conditions were confirmed

#### Solderability

OSHIBA

- (1) Use of Sn-63Pb solder Bath
  - solder bath temperature = 230°C
  - · dipping time = 5 seconds
  - the number of times = once
  - use of R-type flux
- (2) Use of Sn-3.0Ag-0.5Cu solder Bath
  - $\cdot$  solder bath temperature = 245°C
  - $\cdot$  dipping time = 5 seconds
  - $\cdot$  the number of times = once
  - use of R-type flux

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